

AMENDMENTS TO THE CLAIMS

1. (original) A liquid epoxy resin composition comprising

(A) a liquid epoxy resin,

(B) an aromatic amine curing agent having a phenolic hydroxyl group in a skeleton, and

(C) an inorganic filler.

2. (original) The composition of claim 1, further comprising a silicone-modified resin in the form of a copolymer which is obtained from an alkenyl group-containing epoxy resin or phenolic resin and an organopolysiloxane having the average compositional formula (6):



wherein R^5 is a substituted or unsubstituted monovalent hydrocarbon group, "a" is a number of 0.01 to 0.1, "b" is a number of 1.8 to 2.2, and $1.81 \leq a+b \leq 2.3$, said organopolysiloxane containing per molecule 20 to 400 silicon atoms and 1 to 5 hydrogen atoms each directly attached to a silicon atom (i.e., SiH groups), by effecting addition reaction between alkenyl groups and SiH groups.

3. (original) A semiconductor device which is encapsulated with the liquid epoxy resin composition of claim 1 in the cured state.

5. (new) The liquid epoxy resin composition of claim 1, wherein component (A) is bisphenol F-type epoxy resin, component (B) is tetraethyldiaminophenylmethane, and component (C) is spherical silica.

Cc1cc(C)c(N)cc1C2=CC(=C(C)C)C(O)=C2C3=CC(=C(C)C)C(O)=C3C4=CC(=C(C)C)C(N)=CC4[illegible]
$$\text{and} \quad \text{H}-\text{Si}\begin{matrix} \text{CH}_3 \\ | \\ \text{CH}_3 \end{matrix}\text{O}-\left(\text{Si}\begin{matrix} \text{CH}_3 \\ | \\ \text{CH}_3 \end{matrix}\text{O}\right)_{100}-\text{Si}\begin{matrix} \text{CH}_3 \\ | \\ \text{CH}_3 \end{matrix}\text{H}$$